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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	2.375V ~ 2.625V
Number of Logic Elements/Blocks	16
Number of Macrocells	256
Number of Gates	5000
Number of I/O	164
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7256bqc208-7

...and More Features

- System-level features
 - MultiVolt™ I/O interface enabling device core to run at 2.5 V, while I/O pins are compatible with 3.3-V, 2.5-V, and 1.8-V logic levels
 - Programmable power-saving mode for 50% or greater power reduction in each macrocell
 - Fast input setup times provided by a dedicated path from I/O pin to macrocell registers
 - Support for advanced I/O standards, including SSTL-2 and SSTL-3, and GTL+
 - Bus-hold option on I/O pins
 - PCI compatible
 - Bus-friendly architecture including programmable slew-rate control
 - Open-drain output option
 - Programmable security bit for protection of proprietary designs
 - Built-in boundary-scan test circuitry compliant with IEEE Std. 1149.1
 - Supports hot-socketing operation
 - Programmable ground pins
- Advanced architecture features
 - Programmable interconnect array (PIA) continuous routing structure for fast, predictable performance
 - Configurable expander product-term distribution, allowing up to 32 product terms per macrocell
 - Programmable macrocell registers with individual clear, preset, clock, and clock enable controls
 - Two global clock signals with optional inversion
 - Programmable power-up states for macrocell registers
 - 6 to 10 pin- or logic-driven output enable signals
- Advanced package options
 - Pin counts ranging from 44 to 256 in a variety of thin quad flat pack (TQFP), plastic quad flat pack (PQFP), ball-grid array (BGA), space-saving FineLine BGA™, 0.8-mm Ultra FineLine BGA, and plastic J-lead chip carrier (PLCC) packages
 - Pin-compatibility with other MAX 7000B devices in the same package
- Advanced software support
 - Software design support and automatic place-and-route provided by Altera's MAX+PLUS® II development system for Windows-based PCs and Sun SPARCstation, and HP 9000 Series 700/800 workstations

MAX 7000B devices provide programmable speed/power optimization. Speed-critical portions of a design can run at high speed/full power, while the remaining portions run at reduced speed/low power. This speed/power optimization feature enables the designer to configure one or more macrocells to operate up to 50% lower power while adding only a nominal timing delay. MAX 7000B devices also provide an option that reduces the slew rate of the output buffers, minimizing noise transients when non-speed-critical signals are switching. The output drivers of all MAX 7000B devices can be set for 3.3 V, 2.5 V, or 1.8 V and all input pins are 3.3-V, 2.5-V, and 1.8-V tolerant, allowing MAX 7000B devices to be used in mixed-voltage systems.

MAX 7000B devices are supported by Altera development systems, which are integrated packages that offer schematic, text—including VHDL, Verilog HDL, and the Altera Hardware Description Language (AHDL)—and waveform design entry, compilation and logic synthesis, simulation and timing analysis, and device programming. Altera software provides EDIF 2.0.0 and 3.0.0, LPM, VHDL, Verilog HDL, and other interfaces for additional design entry and simulation support from other industry-standard PC- and UNIX-workstation-based EDA tools. Altera software runs on Windows-based PCs, as well as Sun SPARCstation, and HP 9000 Series 700/800 workstations.



For more information on development tools, see the *MAX+PLUS II Programmable Logic Development System & Software Data Sheet* and the *Quartus Programmable Logic Development System & Software Data Sheet*.

Functional Description

The MAX 7000B architecture includes the following elements:

- LABs
- Macrocells
- Expander product terms (shareable and parallel)
- PIA
- I/O control blocks

The MAX 7000B architecture includes four dedicated inputs that can be used as general-purpose inputs or as high-speed, global control signals (clock, clear, and two output enable signals) for each macrocell and I/O pin. [Figure 1](#) shows the architecture of MAX 7000B devices.

The Altera development system automatically optimizes product-term allocation according to the logic requirements of the design.

For registered functions, each macrocell flipflop can be individually programmed to implement D, T, JK, or SR operation with programmable clock control. The flipflop can be bypassed for combinatorial operation. During design entry, the designer specifies the desired flipflop type; the MAX+PLUS II software then selects the most efficient flipflop operation for each registered function to optimize resource utilization.

Each programmable register can be clocked in three different modes:

- Global clock signal. This mode achieves the fastest clock-to-output performance.
- Global clock signal enabled by an active-high clock enable. A clock enable is generated by a product term. This mode provides an enable on each flipflop while still achieving the fast clock-to-output performance of the global clock.
- Array clock implemented with a product term. In this mode, the flipflop can be clocked by signals from buried macrocells or I/O pins.

Two global clock signals are available in MAX 7000B devices. As shown in [Figure 1](#), these global clock signals can be the true or the complement of either of the global clock pins, GCLK1 or GCLK2.

Each register also supports asynchronous preset and clear functions. As shown in [Figure 2](#), the product-term select matrix allocates product terms to control these operations. Although the product-term-driven preset and clear from the register are active high, active-low control can be obtained by inverting the signal within the logic array. In addition, each register clear function can be individually driven by the active-low dedicated global clear pin (GCLRn). Upon power-up, each register in a MAX 7000B device may be set to either a high or low state. This power-up state is specified at design entry.

All MAX 7000B I/O pins have a fast input path to a macrocell register. This dedicated path allows a signal to bypass the PIA and combinatorial logic and be clocked to an input D flipflop with an extremely fast input setup time. The input path from the I/O pin to the register has a programmable delay element that can be selected to either guarantee zero hold time or to get the fastest possible set-up time (as fast as 1.0 ns).

Expander Product Terms

Although most logic functions can be implemented with the five product terms available in each macrocell, more complex logic functions require additional product terms. Another macrocell can be used to supply the required logic resources. However, the MAX 7000B architecture also offers both shareable and parallel expander product terms (“expanders”) that provide additional product terms directly to any macrocell in the same LAB. These expanders help ensure that logic is synthesized with the fewest possible logic resources to obtain the fastest possible speed.

Shareable Expanders

Each LAB has 16 shareable expanders that can be viewed as a pool of uncommitted single product terms (one from each macrocell) with inverted outputs that feed back into the logic array. Each shareable expander can be used and shared by any or all macrocells in the LAB to build complex logic functions. A small delay (t_{SEXP}) is incurred when shareable expanders are used. [Figure 3](#) shows how shareable expanders can feed multiple macrocells.

Figure 3. MAX 7000B Shareable Expanders

Shareable expanders can be shared by any or all macrocells in an LAB.

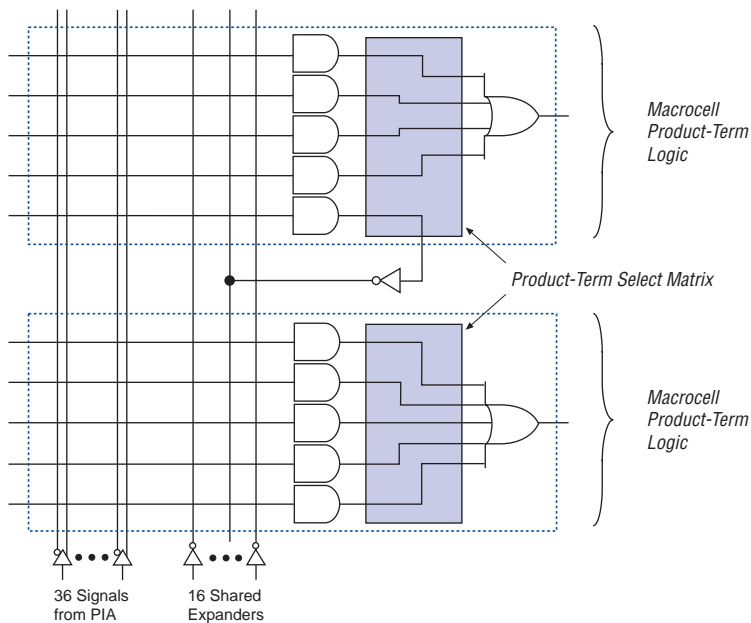
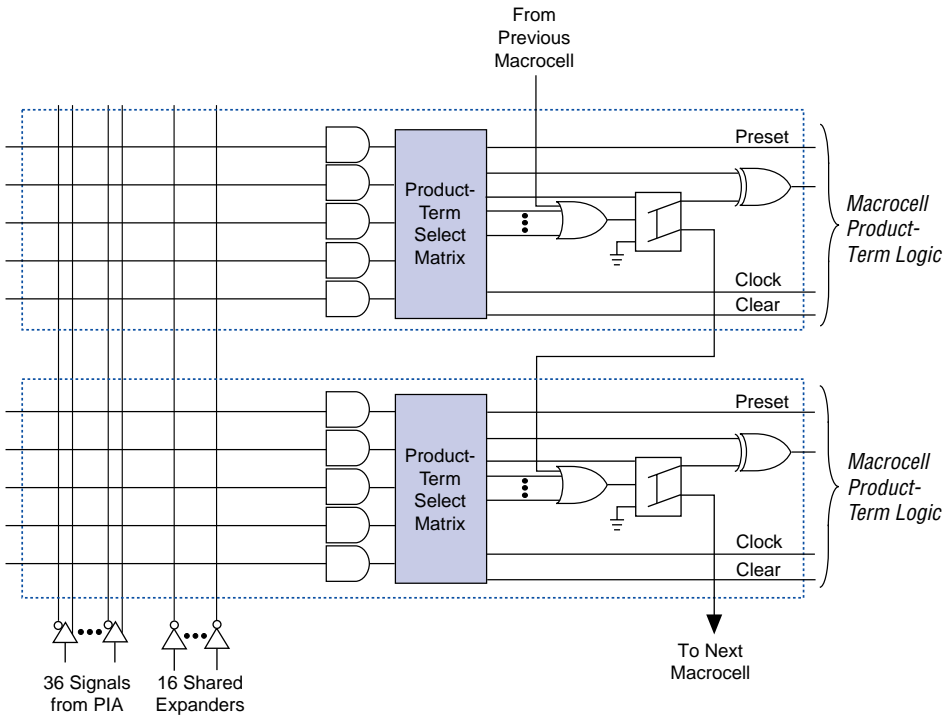


Figure 4. MAX 7000B Parallel Expanders

Unused product terms in a macrocell can be allocated to a neighboring macrocell.



Programmable Interconnect Array

Logic is routed between LABs on the PIA. This global bus is a programmable path that connects any signal source to any destination on the device. All MAX 7000B dedicated inputs, I/O pins, and macrocell outputs feed the PIA, which makes the signals available throughout the entire device. Only the signals required by each LAB are actually routed from the PIA into the LAB. Figure 5 shows how the PIA signals are routed into the LAB. An EEPROM cell controls one input to a two-input AND gate, which selects a PIA signal to drive into the LAB.

In-System Programmability (ISP)

MAX 7000B devices can be programmed in-system via an industry-standard 4-pin IEEE Std. 1149.1 (JTAG) interface. ISP offers quick, efficient iterations during design development and debugging cycles. The MAX 7000B architecture internally generates the high programming voltages required to program EEPROM cells, allowing in-system programming with only a single 2.5-V power supply. During in-system programming, the I/O pins are tri-stated and weakly pulled-up to eliminate board conflicts. The pull-up value is nominally 50 k Ω .

MAX 7000B devices have an enhanced ISP algorithm for faster programming. These devices also offer an ISP_Done bit that provides safe operation when in-system programming is interrupted. This ISP_Done bit, which is the last bit programmed, prevents all I/O pins from driving until the bit is programmed.

ISP simplifies the manufacturing flow by allowing devices to be mounted on a PCB with standard pick-and-place equipment before they are programmed. MAX 7000B devices can be programmed by downloading the information via in-circuit testers, embedded processors, the Altera MasterBlaster communications cable, and the ByteBlasterMV parallel port download cable. Programming the devices after they are placed on the board eliminates lead damage on high-pin-count packages (e.g., QFP packages) due to device handling. MAX 7000B devices can be reprogrammed after a system has already shipped to the field. For example, product upgrades can be performed in the field via software or modem.

In-system programming can be accomplished with either an adaptive or constant algorithm. An adaptive algorithm reads information from the unit and adapts subsequent programming steps to achieve the fastest possible programming time for that unit. A constant algorithm uses a pre-defined (non-adaptive) programming sequence that does not take advantage of adaptive algorithm programming time improvements. Some in-circuit testers cannot program using an adaptive algorithm. Therefore, a constant algorithm must be used. MAX 7000B devices can be programmed with either an adaptive or constant (non-adaptive) algorithm.

The Jam Standard Test and Programming Language (STAPL), JEDEC standard JESD-71, can be used to program MAX 7000B devices with in-circuit testers, PCs, or embedded processors.



For more information on using the Jam language, see [Application Note 88 \(Using the Jam Language for ISP & ICR via an Embedded Processor\)](#) and [Application Note 122 \(Using STAPL for ISP & ICR via an Embedded Processor\)](#).

The ISP circuitry in MAX 7000B devices is compliant with the IEEE Std. 1532 specification. The IEEE Std. 1532 is a standard developed to allow concurrent ISP between multiple PLD vendors.

The instruction register length of MAX 7000B devices is ten bits. The MAX 7000B USERCODE register length is 32 bits. [Tables 7 and 8](#) show the boundary-scan register length and device IDCODE information for MAX 7000B devices.

Table 7. MAX 7000B Boundary-Scan Register Length

Device	Boundary-Scan Register Length
EPM7032B	96
EPM7064B	192
EPM7128B	288
EPM7256B	480
EPM7512B	624

Table 8. 32-Bit MAX 7000B Device IDCODE *Note (1)*

Device	IDCODE (32 Bits)			
	Version (4 Bits)	Part Number (16 Bits)	Manufacturer's Identity (11 Bits)	1 (1 Bit) (2)
EPM7032B	0010	0111 0000 0011 0010	00001101110	1
EPM7064B	0010	0111 0000 0110 0100	00001101110	1
EPM7128B	0010	0111 0001 0010 1000	00001101110	1
EPM7256B	0010	0111 0010 0101 0110	00001101110	1
EPM7512B	0010	0111 0101 0001 0010	00001101110	1

Notes:

- (1) The most significant bit (MSB) is on the left.
- (2) The least significant bit (LSB) for all JTAG IDCODEs is 1.



See [Application Note 39 \(IEEE 1149.1 \(JTAG\) Boundary-Scan Testing in Altera Devices\)](#) for more information on JTAG boundary-scan testing.

[Figure 8](#) shows the timing information for the JTAG signals.

Programmable Speed/Power Control

MAX 7000B devices offer a power-saving mode that supports low-power operation across user-defined signal paths or the entire device. This feature allows total power dissipation to be reduced by 50% or more, because most logic applications require only a small fraction of all gates to operate at maximum frequency.

The designer can program each individual macrocell in a MAX 7000B device for either high-speed or low-power operation. As a result, speed-critical paths in the design can run at high speed, while the remaining paths can operate at reduced power. Macrocells that run at low power incur a nominal timing delay adder (t_{LPA}) for the t_{LAD} , t_{LAC} , t_{IC} , t_{ACL} , t_{CPW} , t_{EN} , and t_{SEXP} parameters.

Output Configuration

MAX 7000B device outputs can be programmed to meet a variety of system-level requirements.

MultiVolt I/O Interface

The MAX 7000B device architecture supports the MultiVolt I/O interface feature, which allows MAX 7000B devices to connect to systems with differing supply voltages. MAX 7000B devices in all packages can be set for 3.3-V, 2.5-V, or 1.8-V pin operation. These devices have one set of V_{CC} pins for internal operation and input buffers (V_{CCINT}), and another set for I/O output drivers (V_{CCIO}).

The V_{CCIO} pins can be connected to either a 3.3-V, 2.5-V, or 1.8-V power supply, depending on the output requirements. When the V_{CCIO} pins are connected to a 1.8-V power supply, the output levels are compatible with 1.8-V systems. When the V_{CCIO} pins are connected to a 2.5-V power supply, the output levels are compatible with 2.5-V systems. When the V_{CCIO} pins are connected to a 3.3-V power supply, the output high is at 3.3 V and is therefore compatible with 3.3-V or 5.0-V systems. Devices operating with V_{CCIO} levels of 2.5 V or 1.8 V incur a nominal timing delay adder.

Table 10 describes the MAX 7000B MultiVolt I/O support.

Power Sequencing & Hot-Socketing

Because MAX 7000B devices can be used in a mixed-voltage environment, they have been designed specifically to tolerate any possible power-up sequence. The V_{CCIO} and V_{CCINT} power planes can be powered in any order.

Signals can be driven into MAX 7000B devices before and during power-up (and power-down) without damaging the device. Additionally, MAX 7000B devices do not drive out during power-up. Once operating conditions are reached, MAX 7000B devices operate as specified by the user.

MAX 7000B device I/O pins will not source or sink more than 300 μ A of DC current during power-up. All pins can be driven up to 4.1 V during hot-socketing.

Design Security

All MAX 7000B devices contain a programmable security bit that controls access to the data programmed into the device. When this bit is programmed, a design implemented in the device cannot be copied or retrieved. This feature provides a high level of design security, because programmed data within EEPROM cells is invisible. The security bit that controls this function, as well as all other programmed data, is reset only when the device is reprogrammed.

Generic Testing

MAX 7000B devices are fully functionally tested. Complete testing of each programmable EEPROM bit and all internal logic elements ensures 100% programming yield. AC test measurements are taken under conditions equivalent to those shown in [Figure 11](#). Test patterns can be used and then erased during early stages of the production flow.

Table 17. MAX 7000B Device Capacitance *Note (9)*

Symbol	Parameter	Conditions	Min	Max	Unit
C_{IN}	Input pin capacitance	$V_{IN} = 0\text{ V}$, $f = 1.0\text{ MHz}$		8	pF
$C_{I/O}$	I/O pin capacitance	$V_{OUT} = 0\text{ V}$, $f = 1.0\text{ MHz}$		8	pF

Notes to tables:

- (1) See the *Operating Requirements for Altera Devices Data Sheet*.
- (2) Minimum DC input voltage is -0.5 V . During transitions, the inputs may undershoot to -2.0 V or overshoot to 4.6 V for input currents less than 100 mA and periods shorter than 20 ns .
- (3) All pins, including dedicated inputs, I/O pins, and JTAG pins, may be driven before V_{CCINT} and V_{CCIO} are powered.
- (4) These values are specified under the Recommended Operating Conditions in [Table 15 on page 29](#).
- (5) The parameter is measured with 50% of the outputs each sourcing the specified current. The I_{OH} parameter refers to high-level TTL or CMOS output current.
- (6) The parameter is measured with 50% of the outputs each sinking the specified current. The I_{OL} parameter refers to low-level TTL or CMOS output current.
- (7) This value is specified for normal device operation. During power-up, the maximum leakage current is $\pm 300\text{ }\mu\text{A}$.
- (8) This pull-up exists while devices are being programmed in-system and in unprogrammed devices during power-up. The pull-up resistor is from the pins to V_{CCIO} .
- (9) Capacitance is measured at 25° C and is sample-tested only. Two of the dedicated input pins (OE1 and GCLRN) have a maximum capacitance of 15 pF .
- (10) The POR time for all 7000B devices does not exceed $100\text{ }\mu\text{s}$. The sufficient V_{CCINT} voltage level for POR is 2.375 V . The device is fully initialized within the POR time after V_{CCINT} reaches the sufficient POR voltage level.
- (11) These devices support in-system programming for -40° to 100° C . For in-system programming support between -40° and 0° C , contact Altera Applications.

Table 19. EPM7032B Internal Timing Parameters *Notes (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-3.5		-5.0		-7.5		
			Min	Max	Min	Max	Min	Max	
t_{IN}	Input pad and buffer delay			0.3		0.5		0.7	ns
t_{IO}	I/O input pad and buffer delay			0.3		0.5		0.7	ns
t_{FIN}	Fast input delay			0.9		1.3		2.0	ns
t_{FIND}	Programmable delay adder for fast input			1.0		1.5		1.5	ns
t_{SEXP}	Shared expander delay			1.5		2.1		3.2	ns
t_{PEXP}	Parallel expander delay			0.4		0.6		0.9	ns
t_{LAD}	Logic array delay			1.4		2.0		3.1	ns
t_{LAC}	Logic control array delay			1.2		1.7		2.6	ns
t_{IOE}	Internal output enable delay			0.1		0.2		0.3	ns
t_{OD1}	Output buffer and pad delay slow slew rate = off $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$		0.9		1.2		1.8	ns
t_{OD3}	Output buffer and pad delay slow slew rate = on $V_{CCIO} = 2.5\text{ V}$ or 3.3 V	$C1 = 35\text{ pF}$		5.9		6.2		6.8	ns
t_{ZX1}	Output buffer enable delay slow slew rate = off $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$		1.6		2.2		3.4	ns
t_{ZX3}	Output buffer enable delay slow slew rate = on $V_{CCIO} = 2.5\text{ V}$ or 3.3 V	$C1 = 35\text{ pF}$		6.6		7.2		8.4	ns
t_{XZ}	Output buffer disable delay	$C1 = 5\text{ pF}$		1.6		2.2		3.4	ns
t_{SU}	Register setup time		0.7		1.1		1.6		ns
t_H	Register hold time		0.4		0.5		0.9		ns
t_{FSU}	Register setup time of fast input		0.8		0.8		1.1		ns
t_{FH}	Register hold time of fast input		1.2		1.2		1.4		ns
t_{RD}	Register delay			0.5		0.6		0.9	ns
t_{COMB}	Combinatorial delay			0.2		0.3		0.5	ns
t_{IC}	Array clock delay			1.2		1.8		2.8	ns
t_{EN}	Register enable time			1.2		1.7		2.6	ns
t_{GLOB}	Global control delay			0.7		1.1		1.6	ns
t_{PRE}	Register preset time			1.0		1.3		1.9	ns
t_{CLR}	Register clear time			1.0		1.3		1.9	ns
t_{PIA}	PIA delay	(2)		0.7		1.0		1.4	ns
t_{LPA}	Low-power adder	(4)		1.5		2.1		3.2	ns

Table 23. EPM7064B Selectable I/O Standard Timing Adder Delays (Part 2 of 2) *Note (1)*

I/O Standard	Parameter	Speed Grade						Unit
		-3		-5		-7		
		Min	Max	Min	Max	Min	Max	
PCI	Input to PIA		0.0		0.0		0.0	ns
	Input to global clock and clear		0.0		0.0		0.0	ns
	Input to fast input register		0.0		0.0		0.0	ns
	All outputs		0.0		0.0		0.0	ns

Notes to tables:

- (1) These values are specified under the Recommended Operating Conditions in [Table 15 on page 29](#). See [Figure 14](#) for more information on switching waveforms.
- (2) These values are specified for a PIA fan-out of all LABs.
- (3) Measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (4) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{ACL} , t_{CPPW} , t_{EN} , and t_{SEXP} parameters for macrocells running in low-power mode.

Table 24. EPM7128B External Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-4		-7		-10		
			Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF (2)		4.0		7.5		10.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF (2)		4.0		7.5		10.0	ns
t _{SU}	Global clock setup time	(2)	2.5		4.5		6.1		ns
t _H	Global clock hold time	(2)	0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		1.0		1.5		1.5		ns
t _{FH}	Global clock hold time of fast input		1.0		1.0		1.0		ns
t _{FZHSU}	Global clock setup time of fast input with zero hold time		2.0		3.0		3.0		ns
t _{FZHH}	Global clock hold time of fast input with zero hold time		0.0		0.0		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF	1.0	2.8	1.0	5.7	1.0	7.5	ns
t _{CH}	Global clock high time		1.5		3.0		4.0		ns
t _{CL}	Global clock low time		1.5		3.0		4.0		ns
t _{ASU}	Array clock setup time	(2)	1.2		2.0		2.8		ns
t _{AH}	Array clock hold time	(2)	0.2		0.7		0.9		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF (2)	1.0	4.1	1.0	8.2	1.0	10.8	ns
t _{ACH}	Array clock high time		1.5		3.0		4.0		ns
t _{ACL}	Array clock low time		1.5		3.0		4.0		ns
t _{CPPW}	Minimum pulse width for clear and preset		1.5		3.0		4.0		ns
t _{CNT}	Minimum global clock period	(2)		4.1		7.9		10.6	ns
f _{CNT}	Maximum internal global clock frequency	(2), (3)	243.9		126.6		94.3		MHz
t _{ACNT}	Minimum array clock period	(2)		4.1		7.9		10.6	ns
f _{ACNT}	Maximum internal array clock frequency	(2), (3)	243.9		126.6		94.3		MHz

Table 27. EPM7256B External Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-5		-7		-10		
			Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF (2)		5.0		7.5		10.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF (2)		5.0		7.5		10.0	ns
t _{SU}	Global clock setup time	(2)	3.3		4.8		6.6		ns
t _H	Global clock hold time	(2)	0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		1.0		1.5		1.5		ns
t _{FH}	Global clock hold time for fast input		1.0		1.0		1.0		ns
t _{FZHSU}	Global clock setup time of fast input with zero hold time		2.5		3.0		3.0		ns
t _{FZHH}	Global clock hold time of fast input with zero hold time		0.0		0.0		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF	1.0	3.3	1.0	5.1	1.0	6.7	ns
t _{CH}	Global clock high time		2.0		3.0		4.0		ns
t _{CL}	Global clock low time		2.0		3.0		4.0		ns
t _{ASU}	Array clock setup time	(2)	1.4		2.0		2.8		ns
t _{AH}	Array clock hold time	(2)	0.4		0.8		1.0		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF (2)	1.0	5.2	1.0	7.9	1.0	10.5	ns
t _{ACH}	Array clock high time		2.0		3.0		4.0		ns
t _{ACL}	Array clock low time		2.0		3.0		4.0		ns
t _{CPPW}	Minimum pulse width for clear and preset		2.0		3.0		4.0		ns
t _{CNT}	Minimum global clock period	(2)		5.3		7.9		10.6	ns
f _{CNT}	Maximum internal global clock frequency	(2), (3)	188.7		126.6		94.3		MHz
t _{ACNT}	Minimum array clock period	(2)		5.3		7.9		10.6	ns
f _{ACNT}	Maximum internal array clock frequency	(2), (3)	188.7		126.6		94.3		MHz

Table 29. EPM7256B Selectable I/O Standard Timing Adder Delays (Part 1 of 2) *Note (1)*

I/O Standard	Parameter	Speed Grade						Unit
		-5		-7		-10		
		Min	Max	Min	Max	Min	Max	
3.3 V TTL/CMOS	Input to PIA		0.0		0.0		0.0	ns
	Input to global clock and clear		0.0		0.0		0.0	ns
	Input to fast input register		0.0		0.0		0.0	ns
	All outputs		0.0		0.0		0.0	ns
2.5 V TTL/CMOS	Input to PIA		0.4		0.6		0.8	ns
	Input to global clock and clear		0.3		0.5		0.6	ns
	Input to fast input register		0.2		0.3		0.4	ns
	All outputs		0.2		0.3		0.4	ns
1.8 V TTL/CMOS	Input to PIA		0.6		0.9		1.2	ns
	Input to global clock and clear		0.6		0.9		1.2	ns
	Input to fast input register		0.5		0.8		1.0	ns
	All outputs		1.3		2.0		2.6	ns
SSTL-2 Class I	Input to PIA		1.5		2.3		3.0	ns
	Input to global clock and clear		1.3		2.0		2.6	ns
	Input to fast input register		1.1		1.7		2.2	ns
	All outputs		0.0		0.0		0.0	ns
SSTL-2 Class II	Input to PIA		1.5		2.3		3.0	ns
	Input to global clock and clear		1.3		2.0		2.6	ns
	Input to fast input register		1.1		1.7		2.2	ns
	All outputs		−0.1		−0.2		−0.2	ns
SSTL-3 Class I	Input to PIA		1.4		2.1		2.8	ns
	Input to global clock and clear		1.1		1.7		2.2	ns
	Input to fast input register		1.0		1.5		2.0	ns
	All outputs		0.0		0.0		0.0	ns
SSTL-3 Class II	Input to PIA		1.4		2.1		2.8	ns
	Input to global clock and clear		1.1		1.7		2.2	ns
	Input to fast input register		1.0		1.5		2.0	ns
	All outputs		0.0		0.0		0.0	ns
GTL+	Input to PIA		1.8		2.7		3.6	ns
	Input to global clock and clear		1.8		2.7		3.6	ns
	Input to fast input register		1.7		2.6		3.4	ns
	All outputs		0.0		0.0		0.0	ns

Table 29. EPM7256B Selectable I/O Standard Timing Adder Delays (Part 2 of 2) *Note (1)*

I/O Standard	Parameter	Speed Grade						Unit
		-5		-7		-10		
		Min	Max	Min	Max	Min	Max	
PCI	Input to PIA		0.0		0.0		0.0	ns
	Input to global clock and clear		0.0		0.0		0.0	ns
	Input to fast input register		0.0		0.0		0.0	ns
	All outputs		0.0		0.0		0.0	ns

Notes to tables:

- (1) These values are specified under the Recommended Operating Conditions in Table 15 on page 29. See Figure 14 for more information on switching waveforms.
- (2) These values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (3) Measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (4) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{ACL} , t_{CPW} , t_{EN} , and t_{SEXP} parameters for macrocells running in low-power mode.

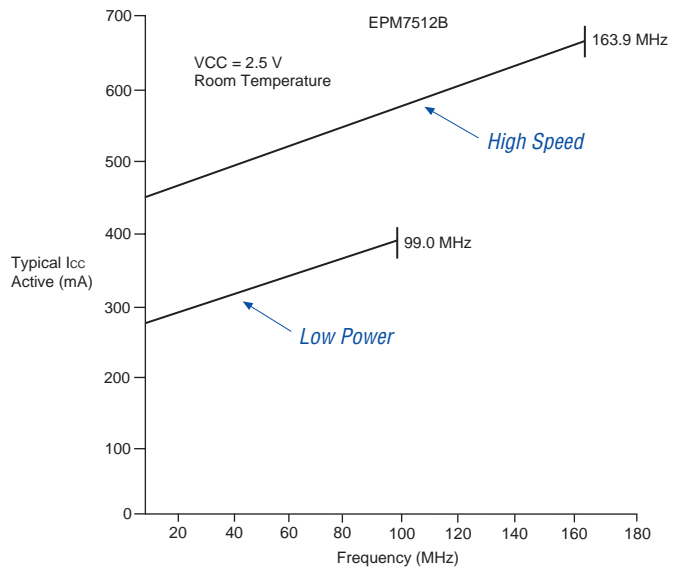
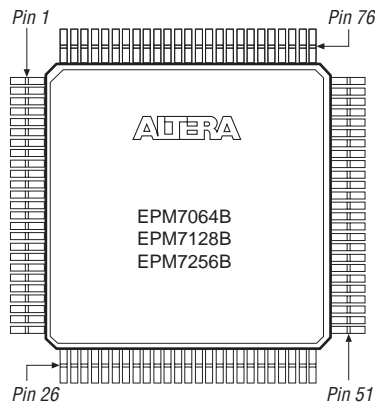
Figure 19. I_{CC} vs. Frequency for EPM7512B Devices

Figure 23. 100-Pin TQFP Package Pin-Out Diagram

Package outline not drawn to scale.

**Figure 24. 100-Pin FineLine BGA Package Pin-Out Diagram**

Package outline not drawn to scale.

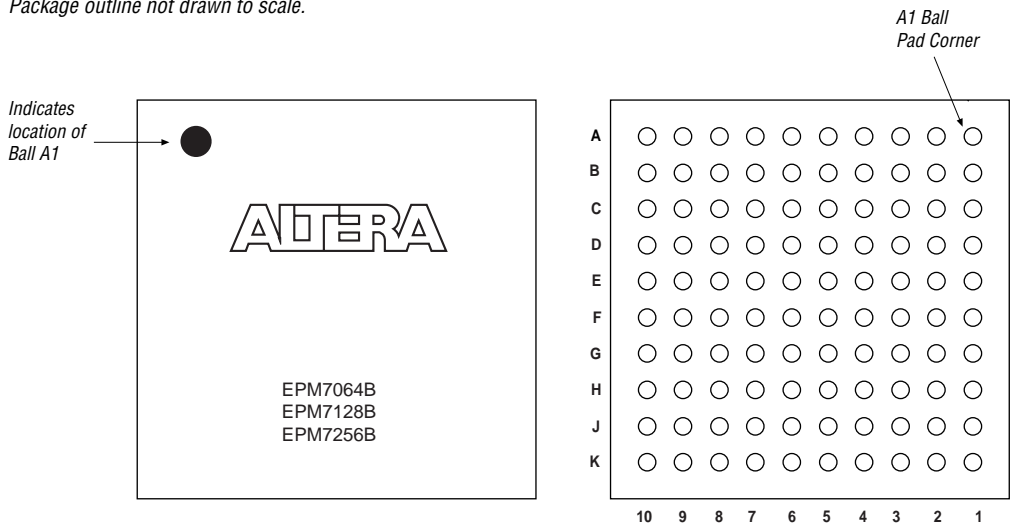


Figure 25. 144-Pin TQFP Package Pin-Out Diagram

Package outline not drawn to scale.

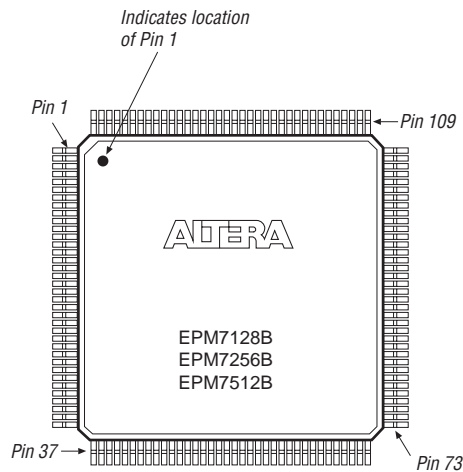
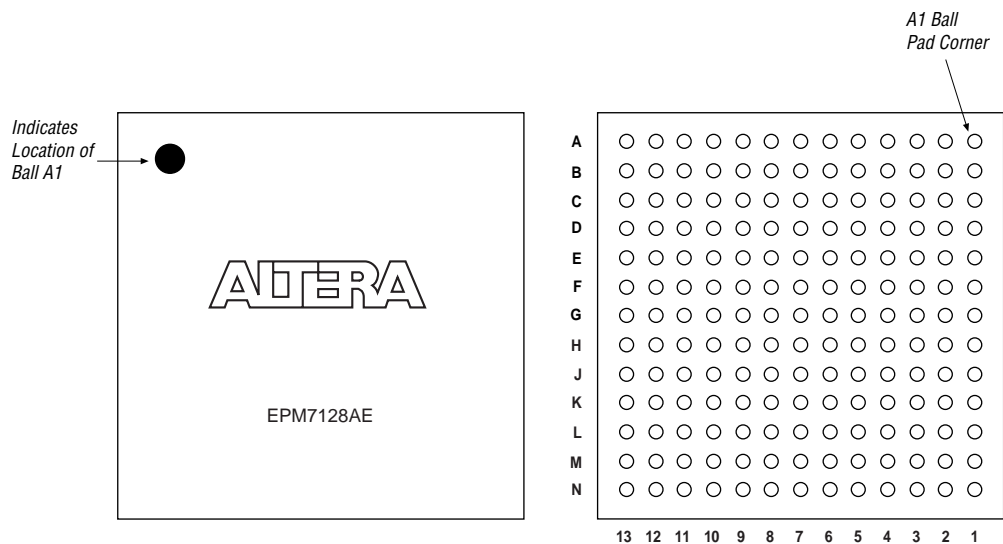


Figure 26. 169-Pin Ultra FineLine BGA Pin-Out Diagram

Package outline not drawn to scale.



Version 3.3

The following changes were made to the *MAX 7000B Programmable Logic Device Family Data Sheet* version 3.3:

- Updated [Table 3](#).
- Added [Tables 4](#) through [6](#).

Version 3.2

The following changes were made to the *MAX 7000B Programmable Logic Device Family Data Sheet* version 3.2:

- Updated [Note \(10\)](#) and added ambient temperature (T_A) information to [Table 15](#).

Version 3.1

The following changes were made to the *MAX 7000B Programmable Logic Device Family Data Sheet* version 3.1:

- Updated V_{IH} and V_{IL} specifications in [Table 16](#).
- Updated leakage current conditions in [Table 16](#).

Version 3.0

The following changes were made to the *MAX 7000B Programmable Logic Device Family Data Sheet* version 3.0:

- Updated timing numbers in [Table 1](#).
- Updated [Table 16](#).
- Updated timing in [Tables 18, 19, 21, 22, 24, 25, 27, 28, 30, and 31](#).



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